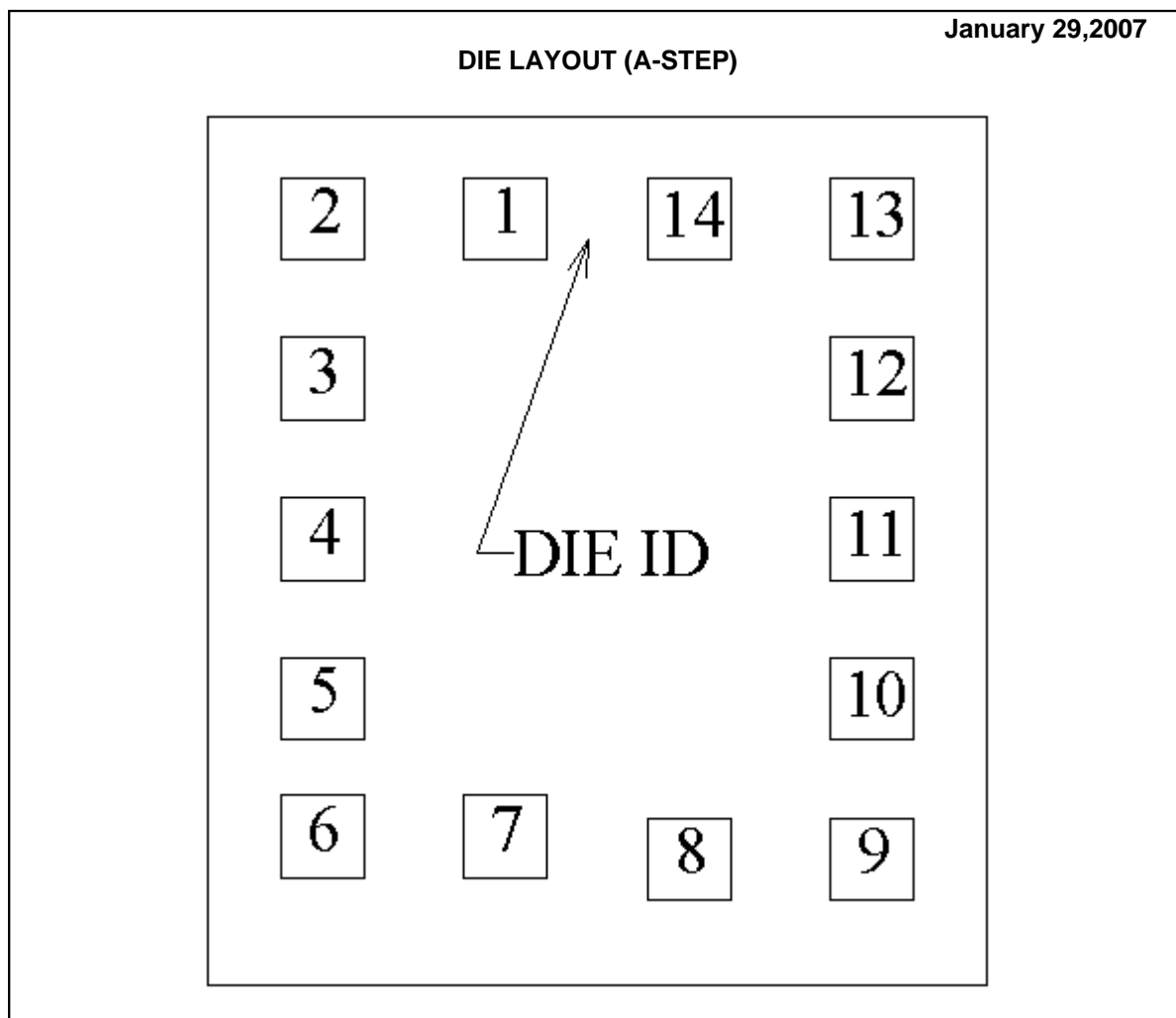


**LM3046 MDC MWC  
TRANSISTOR ARRAY**



**DIE/WAFER CHARACTERISTICS**

Fabrication Attributes		General Die Information	
Physical Die Identification	3146A	Bond Pad Opening Size (min)	91µm x 91µm
Die Step	A	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	150mm	Back Side Metal	BARE BACK
Die Size (Drawn)	864µm x 965µm 34.0mils x 38.0mils	Back Side Connection	
Thickness	406µm Nominal		
Min Pitch	152µm Nominal		

**Special Assembly Requirements:**

**Note: Actual die size is rounded to the nearest micron.**

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**Die Bond Pad Coordinate Locations (A -Step)**

(Referenced to die center, coordinates in  $\mu\text{m}$ ) **NC** = No Connection, **N.U.** = Not Used

SIGNAL NAME	PAD# NUMBER	X/Y COORDINATES		PAD SIZE		
		X	Y	X	Y	
Pad	1	-102	369	91	x	91
Q1 BASE	2	-305	369	91	x	91
Pad	3	-305	191	91	x	91
Q2 BASE	4	-305	13	91	x	91
Pad	5	-305	-164	91	x	91
Q3 BASE	6	-305	-317	91	x	91
Pad	7	-102	-317	91	x	91
Pad	8	102	-342	91	x	91
Q4 BASE	9	305	-342	91	x	91
Pad	10	305	-164	91	x	91
Pad	11	305	13	91	x	91
Q5 BASE	12	305	191	91	x	91
SUBSTRATE	13	305	369	91	x	91
Pad	14	102	369	91	x	91

**LM3046 MDC MWC  
TRANSISTOR ARRAY**

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